

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $\pi$ -MOSV)

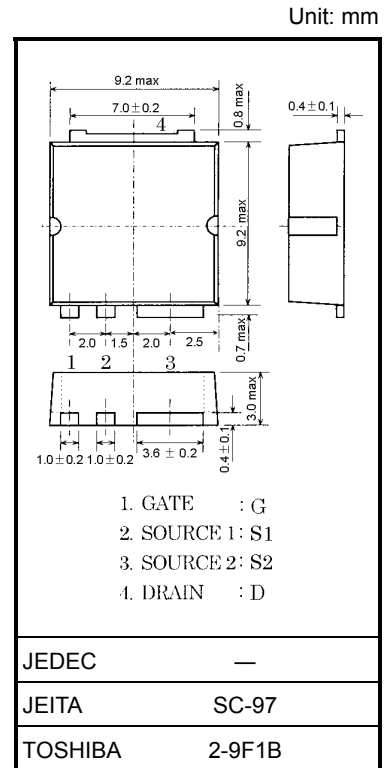
# 2SK3444

Switching Regulator, DC-DC Converter Applications  
Motor Drive Applications

- Low drain-source ON resistance:  $R_{DS(ON)} = 65 \text{ m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 10 \text{ S}$  (typ.)
- Low leakage current:  $I_{DSS} = 100 \mu\text{A}$  ( $V_{DS} = 200 \text{ V}$ )
- Enhancement mode:  $V_{th} = 3.0 \text{ to } 5.0 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 1 \text{ mA}$ )

### Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

| Characteristics                                      |                | Symbol    | Rating     | Unit             |
|--|----------------|-----------|------------|------------------|
| Drain-source voltage                                 |                | $V_{DSS}$ | 200        | V                |
| Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ ) |                | $V_{DGR}$ | 200        | V                |
| Gate-source voltage                                  |                | $V_{GSS}$ | $\pm 30$   | V                |
| Drain current  | DC (Note 1)    | $I_D$     | 25         | A                |
|  | Pulse (Note 1) | $I_{DP}$  | 100        |                  |
| Drain power dissipation ( $T_c = 25^\circ\text{C}$ ) |                | $P_D$     | 125        | W                |
| Single pulse avalanche energy (Note 2)               |                | $E_{AS}$  | 488        | mJ               |
| Avalanche current                                    |                | $I_{AR}$  | 25         | A                |
| Repetitive avalanche energy (Note 3)                 |                | $E_{AR}$  | 12.5       | mJ               |
| Channel temperature                                  |                | $T_{ch}$  | 150        | $^\circ\text{C}$ |
| Storage temperature range                            |                | $T_{stg}$ | -55 to 150 | $^\circ\text{C}$ |



Weight: 0.74 g (typ.)

### Thermal Characteristics

| Characteristics                     | Symbol         | Max  | Unit               |
|-------------------------------------|----------------|------|--------------------|
| Thermal resistance, channel to case | $R_{th(ch-c)}$ | 1.00 | $^\circ\text{C/W}$ |

Notice:

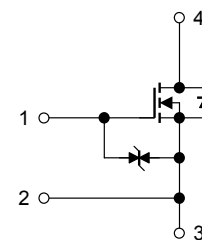
Please use the S1 pin for gate input signal return. Make sure that the main current flows into the S2 pin.

Note 1: Ensure that the channel temperature does not exceed  $150^\circ\text{C}$ .

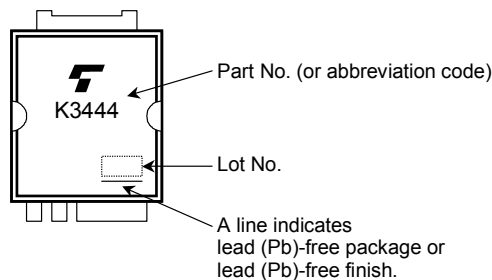
Note 2:  $V_{DD} = 50 \text{ V}$ ,  $T_{ch} = 25^\circ\text{C}$  (initial),  $L = 1.26 \text{ mH}$ ,  $I_{AR} = 25 \text{ A}$ ,  $R_G = 25 \Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



### Marking



**Electrical Characteristics (Note 4) (Ta = 25°C)**

| Characteristics                                 |               | Symbol        | Test Condition   | Min                                       | Typ. | Max      | Unit             |
|---|---------------|---------------|--|---|------|----------|------------------|
| Gate leakage current                            |               | $I_{GSS}$     | $V_{GS} = \pm 25\text{ V}, V_{DS} = 0\text{ V}$                        | —   | —    | $\pm 10$ | $\mu\text{A}$    |
| Drain cut-off current                           |               | $I_{DSS}$     | $V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}$                           | —   | —    | 100      | $\mu\text{A}$    |
| Drain-source breakdown voltage                  |               | $V_{(BR)DSS}$ | $I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$                              | 200                                       | —    | —        | V                |
| Gate threshold voltage                          |               | $V_{th}$      | $V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$                              | 3.0                                       | —    | 5.0      | V                |
| Drain-source ON resistance                      |               | $R_{DS(ON)}$  | $V_{GS} = 10\text{ V}, I_D = 12.5\text{ A}$                            | —   | 65   | 82       | $\text{m}\Omega$ |
| Forward transfer admittance                     |               | $ Y_{fs} $    | $V_{DS} = 10\text{ V}, I_D = 12.5\text{ A}$                            | 5   | 10   | —        | S                |
| Input capacitance                               |               | $C_{iss}$     | $V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$          | —   | 2080 | —        | pF               |
| Reverse transfer capacitance                    |               | $C_{rss}$     |  | —   | 280  | —        |                  |
| Output capacitance                              |               | $C_{oss}$     |  | —   | 1060 | —        |                  |
| Switching time                                  | Rise time     | $t_r$         |  | —   | 20   | —        | ns               |
|   | Turn-on time  | $t_{on}$      |  | —   | 40   | —        |                  |
|   | Fall time     | $t_f$         |  | —   | 10   | —        |                  |
|   | Turn-off time | $t_{off}$     |  | Duty $\leq 1\%$ , $t_w = 10\ \mu\text{s}$ | —    | 40       |                  |
| Total gate charge (gate-source plus gate-drain) |               | $Q_g$         | $V_{DD} \approx 160\text{ V}, V_{GS} = 10\text{ V}, I_D = 25\text{ A}$ | —   | 44   | —        | nC               |
| Gate-source charge                              |               | $Q_{gs}$      |  | —   | 21   | —        |                  |
| Gate-drain ("miller") charge                    |               | $Q_{gd}$      |  | —   | 23   | —        |                  |

Note 4: Connect the S1 pin and S2 pin together, and ground them except during switching time measurement.

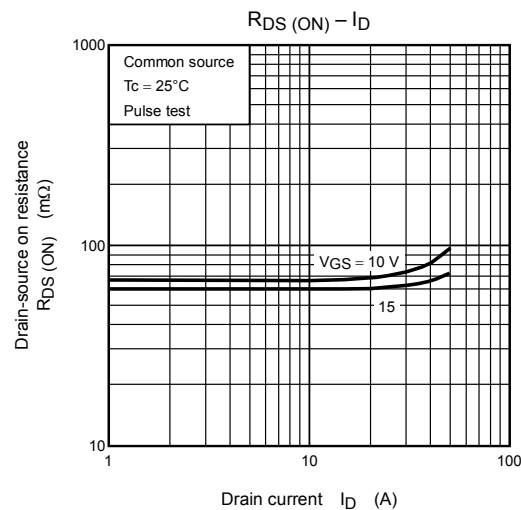
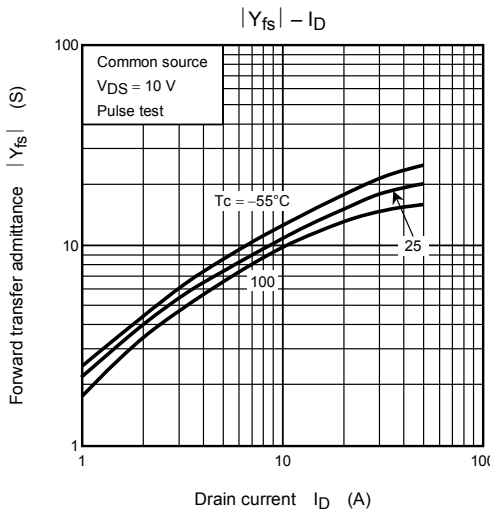
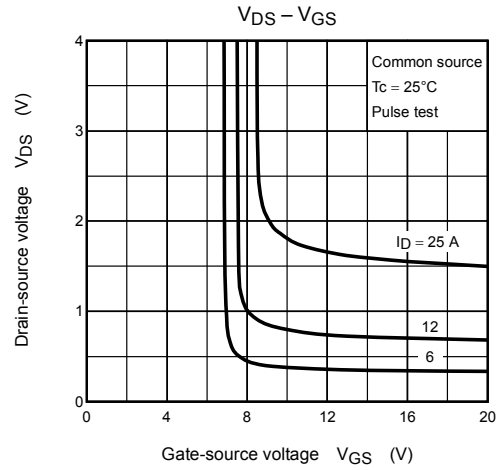
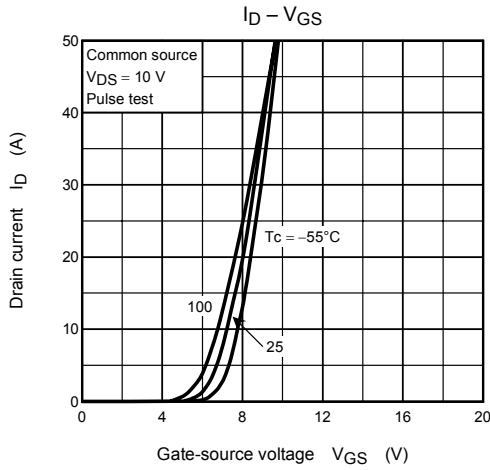
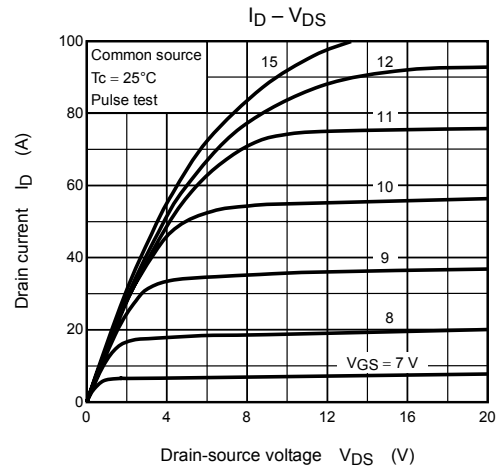
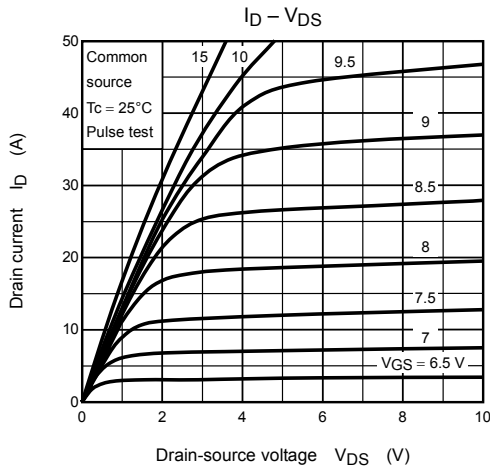
**Source-Drain Diode Ratings and Characteristics (Note 5) (Ta = 25°C)**

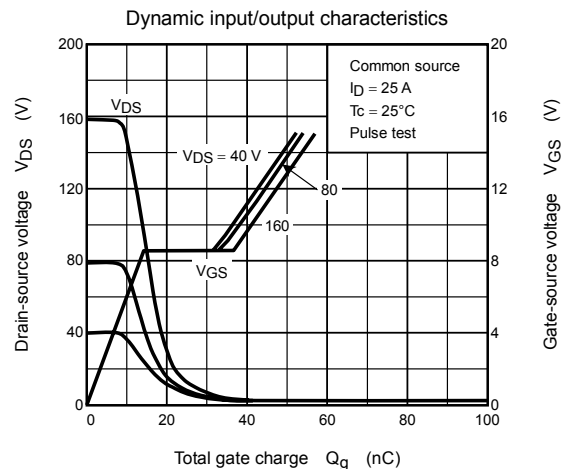
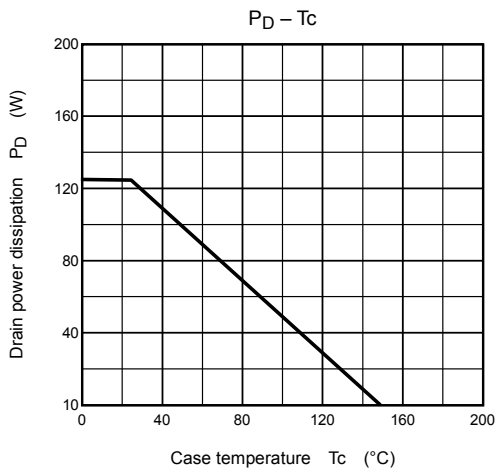
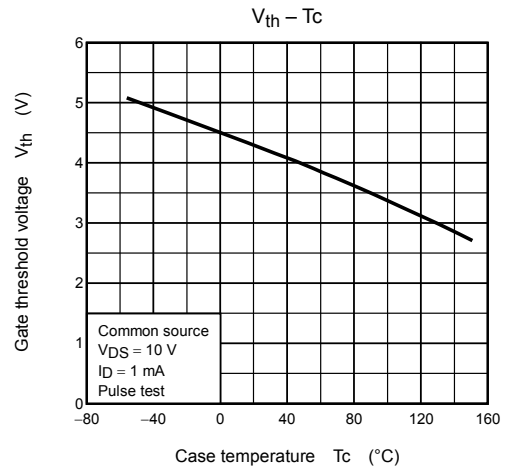
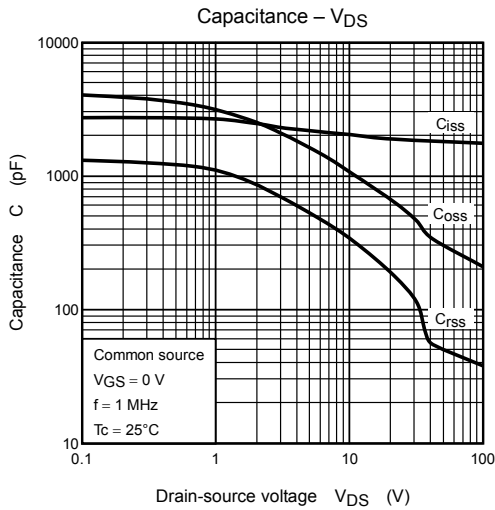
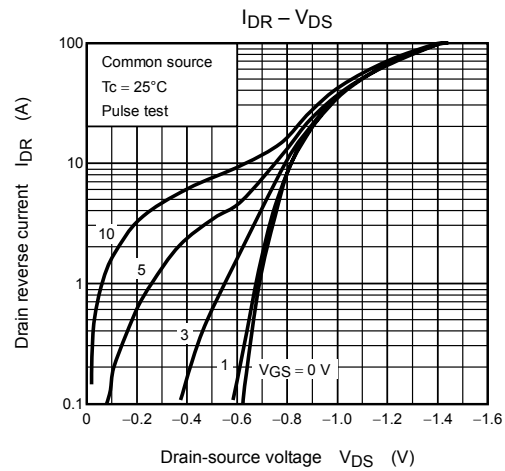
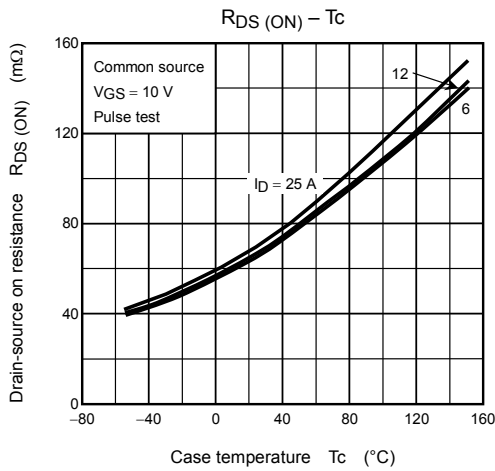
| Characteristics                                   | Symbol     | Test Condition   | Min | Typ. | Max  | Unit          |
|---|------------|--|-----|------|------|---------------|
| Continuous drain reverse current (Note 1, Note 5) | $I_{DR1}$  | —  | —   | —    | 25   | A             |
| Pulse drain reverse current (Note 1, Note 5)      | $I_{DRP1}$ | —  | —   | —    | 100  | A             |
| Continuous drain reverse current (Note 1, Note 5) | $I_{DR2}$  | —  | —   | —    | 1    | A             |
| Pulse drain reverse current (Note 1, Note 5)      | $I_{DRP2}$ | —  | —   | —    | 4    | A             |
| Forward voltage (diode)                           | $V_{DS2F}$ | $I_{DR1} = 25\text{ A}, V_{GS} = 0\text{ V}$                                       | —   | —    | -1.5 | V             |
| Reverse recovery time                             | $t_{rr}$   | $I_{DR} = 25\text{ A}, V_{GS} = 0\text{ V}, dI_{DR}/dt = 100\text{ A}/\mu\text{s}$ | —   | 290  | —    | ns            |
| Reverse recovery charge                           | $Q_{rr}$   |  | —   | 2.2  | —    | $\mu\text{C}$ |

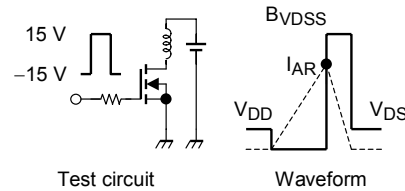
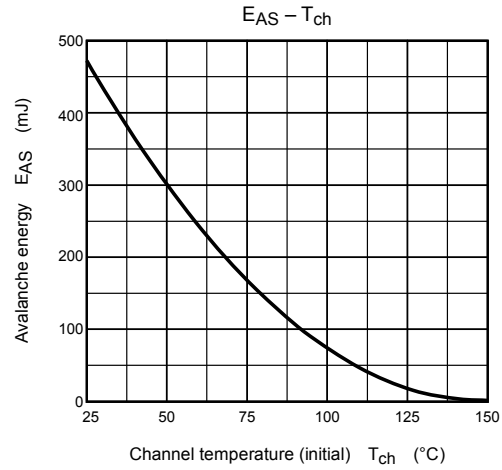
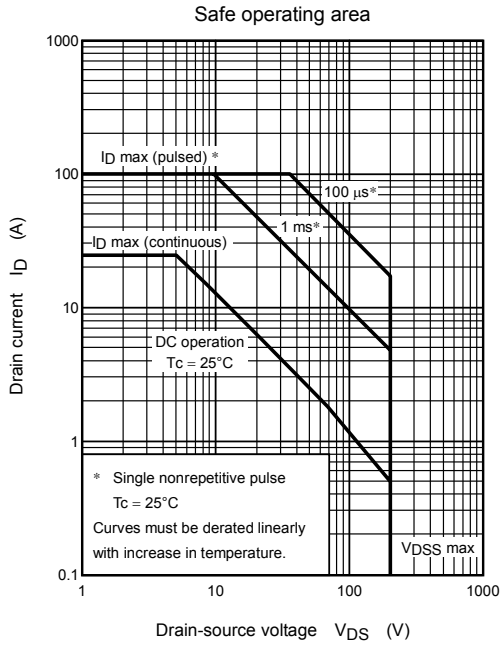
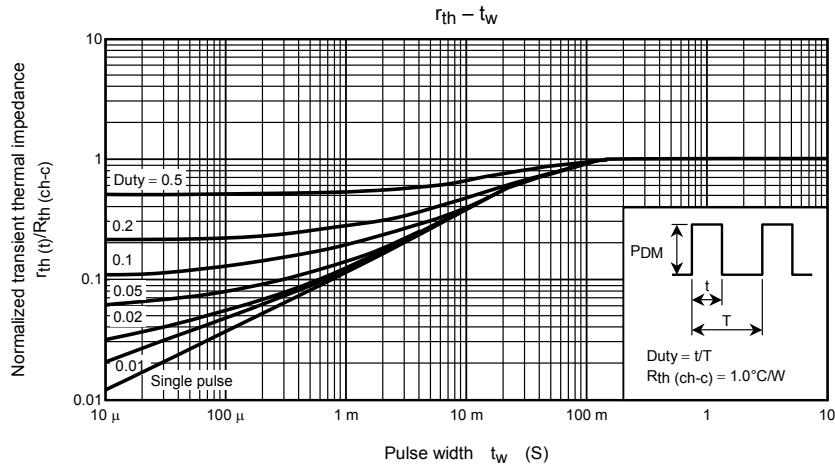
Note 5:  $I_{DR1}, I_{DRP1}$ : Current flowing between the drain and the S2 pin. Ensure that the S1 pin is left open.

$I_{DR2}, I_{DRP2}$ : Current flowing between the drain and the S1 pin. Ensure that the S2 pin is left open.

Unless otherwise specified, connect the S1 and S2 pins together, and ground them.







$R_G = 25 \Omega$   
 $V_{DD} = 50 \text{ V}, L = 1.26 \text{ mH}$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - V_{DD}} \right)$$

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